



- A1
B1 EMS Electronic manufacturing services, PCBs and other circuit carriers
- A2
B2-3 Electromechanics and system peripherals, Interconnection components
- A2
Electromechanics and system peripherals, Interconnection components, Relays, switches and keyboards
- B3 Electromechanics and system peripherals, Interconnection components, Casing technology
- A3 Test and measurement
- A4 Power supplies
- A5
A6 Passive components
- B3 Sensor technology, Micro- and nanosystems (NEMS, MEMS)
- B4 Embedded systems
- B4 Wireless
- B4-5
C3-5 Semiconductors
- B6 Displays
- B6 Automotive
- C1-2 SEMICON EUROPA 2024
- all halls ED/EDA
- all halls Servo-technology
- all halls Assemblies and subsystems
- all halls Services
- ICM **Conferences**

Planning status as of: 7/2023
(Subject to change)

Plan of the fair grounds